





Lead Metallization			
<div> <div></div> <div>Lead Side</div> <div>Substrate Electrode Side</div> <div>Bi distribution</div> </div>	<div> <div>Sn-1Bi</div> <div>Thickness: 10μm</div> </div>	<div> <div>Sn-2Bi/Sn</div> <div>Thickness: 4/6μm</div> </div>	
			
			<div> <div>Homogeneous</div> <div>Heterogeneous</div> </div>

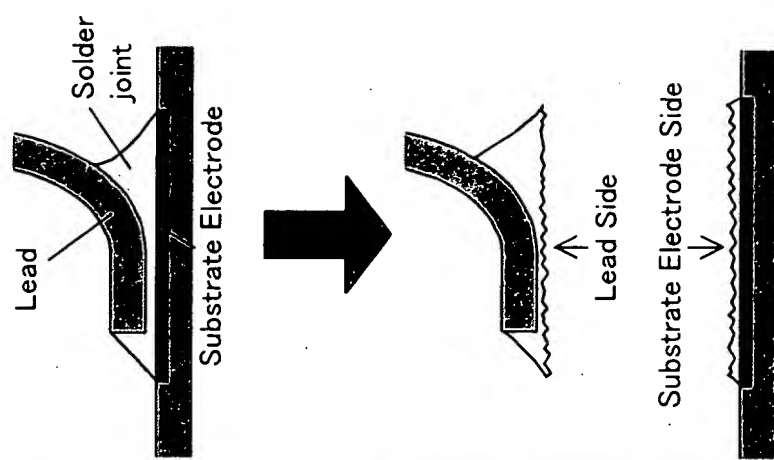


Figure 1 Fracture surface of solder joint (1)

Solder: Sn-2.8Ag-15Bi    Lead: 42 Alloy